

MOSFETs Silicon N-Channel MOS (DTMOSVI)

TK125E60Z1

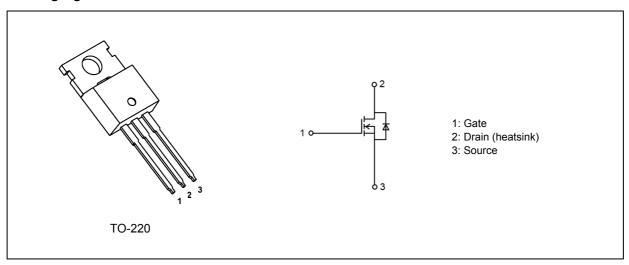
1. Applications

· Switching Power Supplies

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)} = 0.105 \Omega$ (typ.)
- (2) High-speed switching properties with lower capacitance.
- (3) Enhancement mode: $V_{th} = 3 \text{ to } 4 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 0.73 \text{ mA})$

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (T_a = 25 °C unless otherwise specified)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	600	V
Gate-source voltage		V _{GSS}	±30	
Drain current (DC)	(Note 1)	I _D	20	Α
Drain current (pulsed)	(Note 1)	I _{DP}	80]
Power dissipation (T _c = 25 °C)		P _D	150	W
Single-pulse avalanche energy	(Note 2)	E _{AS}	242	mJ
Single-pulse avalanche current		I _{AS}	4.2	Α
Reverse drain current (DC)	(Note 1)	I _{DR}	20	
Reverse drain current (pulsed)	(Note 1)	I _{DRP}	80]
Channel temperature		T _{ch}	150	°C
Storage temperature		T _{stg}	-55 to 150]
Mounting torque		TOR	0.6	N · m

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production

2024-12



5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance	R _{th(ch-c)}	0.833	°C/W
Channel-to-ambient thermal resistance	R _{th(ch-a)}	83.3	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: V_{DD} = 90 V, T_{ch} = 25 °C (initial), L = 24.3 mH, I_{AS} = 4.2 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μА
Drain cut-off current	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	2	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.73 mA	3	_	4	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 6 A	_	0.105	0.125	Ω

6.2. Dynamic Characteristics (Ta = 25 °C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance		C _{iss}	V _{DS} = 300 V, V _{GS} = 0 V, f = 100 kHz	_	1620	_	pF
Reverse transfer capacitance		C _{rss}		_	2.3		
Output capacitance		C _{oss}		_	40	_	
Effective output capacitance (energy related)	(Note 3)	C _{o(er)}	V _{DS} = 0 to 400 V, V _{GS} = 0 V	_	70		
Effective output capacitance (time related)	(Note 4)	C _{o(tr)}		_	480		
Gate resistance		r _g	V _{DS} = OPEN , f = 1 MHz	_	3.2	_	Ω
Switching time (rise time)		t _r	See Figure 6.2.1	_	26	_	ns
Switching time (turn-on time)		t _{on}		_	50		
Switching time (fall time)		t _f		_	5		
Switching time (turn-off time)		t _{off}		_	75	_	
MOSFET dv/dt ruggedness		dv/dt	$V_{DS} \le V_{DSS}$, $I_D \le 10 \text{ A}$	70	_	_	V/ns

Note 3: $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0V to 400V. Note 4: $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0V to 400V.

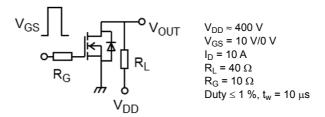


Fig. 6.2.1 Switching Time Test Circuit



6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	_	28		nC
Gate-source charge 1	Q _{gs1}			9		
Gate-drain charge	Q _{gd}		_	8	_	

6.4. Source-Drain Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	V_{DSF}	I _{DR} = 20 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time		V _{DD} = 400 V,	_	285	_	ns
Reverse recovery charge	Q_{rr}	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$ - $dI_{DR}/dt = 100 \text{ A}/\mu\text{s}$	_	3.1	_	μС
Peak reverse recovery current	I _{rr}	αιρκ/αι 100 Α/μδ	_	22	_	Α
Diode dv/dt ruggedness	dv/dt	$V_{DD} \le 400 \text{ V}, I_{DR} \le 10 \text{ A}, V_{GS} = 0 \text{ V}$	40	_	_	V/ns

7. Marking

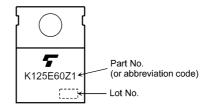


Fig. 7.1 Marking



8. Characteristics Curves (Note)

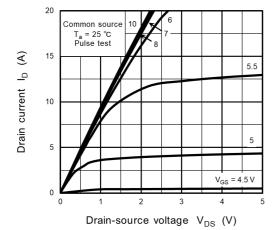
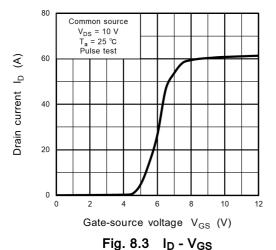
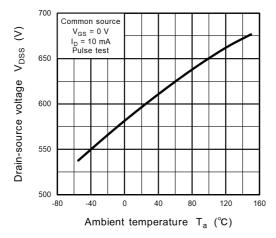
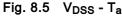


Fig. 8.1 I_D - V_{DS}







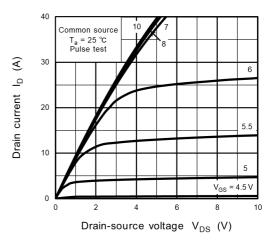


Fig. 8.2 I_D - V_{DS}

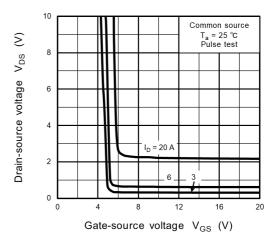


Fig. 8.4 V_{DS} - V_{GS}

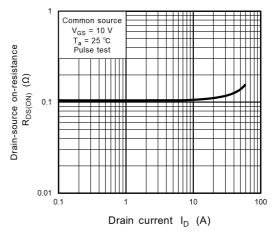


Fig. 8.6 R_{DS(ON)} - I_D



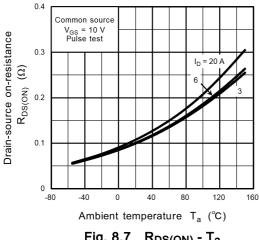


Fig. 8.7 R_{DS(ON)} - T_a

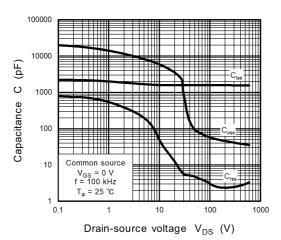
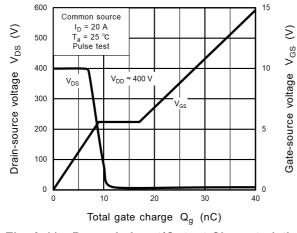


Fig. 8.9 C - V_{DS}



Dynamic Input/Output Characteristics

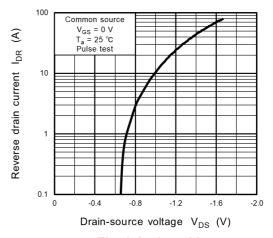


Fig. 8.8 IDR - VDS

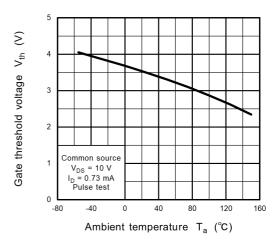


Fig. 8.10 V_{th} - T_a

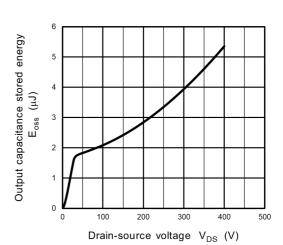


Fig. 8.12 Eoss - V_{DS}



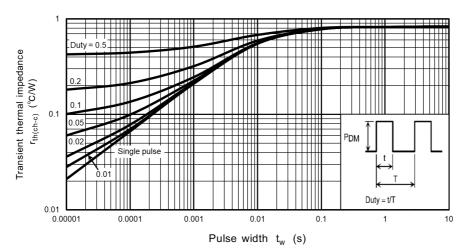


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

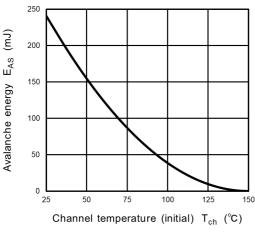
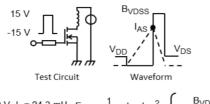


Fig. 8.14 E_{AS} - T_{ch} (Guaranteed Maximum)



 $V_{DD} = 90 \text{ V}, L = 24.3 \text{ mH}$ $E_{AS} = \frac{1}{2} \cdot L \cdot I_{AS}^2 \cdot \left[\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right]$

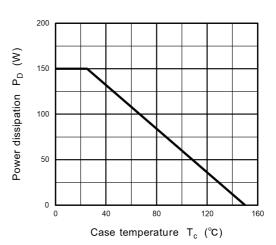


Fig. 8.15 P_D - T_c (Guaranteed Maximum)

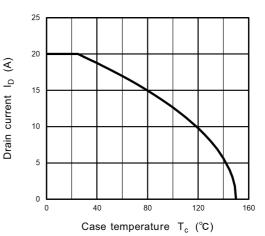


Fig. 8.17 I_D - T_c (Guaranteed Maximum)

Fig. 8.16 Test Circuit/Waveform



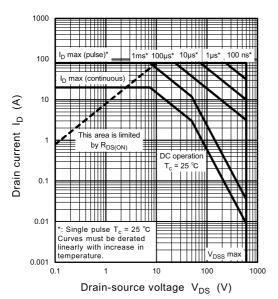


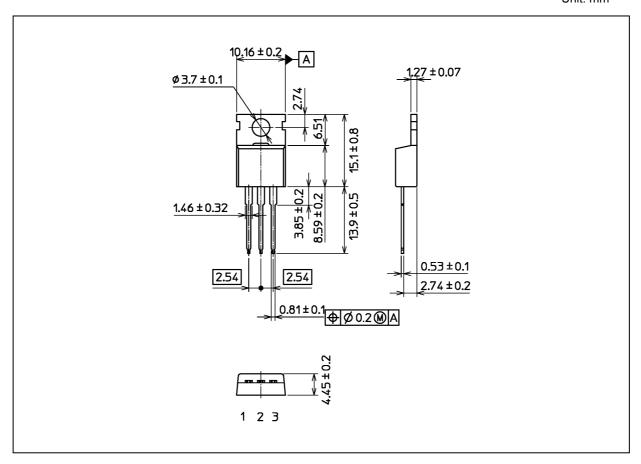
Fig. 8.18 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 1.93 g (typ.)

	Package Name(s)
TOSHIBA: 2-10X1A	
Nickname: TO-220	



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